

SYSTEM AND APPARATUS FOR TESTING PACKAGED DEVICES AND
RELATED METHODS

ABSTRACT OF THE DISCLOSURE

A testing system is disclosed for testing a packaged device having a body with a package profile and an array of contacts coupled to the body. In one embodiment, the system includes a socket having a receiving area and an array of leads arranged to engage the array of contacts on the packaged device. The system of this embodiment also has a package handling assembly with a placement head and an alignment element coupled to the placement head. The alignment element is movable with the placement head as a unit relative to the socket. The alignment element is positionable in the receiving area of the socket. The alignment element restricts movement of the packaged device in at least two dimensions relative to the array of leads when the packaged device is positioned in the receiving area adjacent to the array of leads.